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# FGH60N60SMD\_F085 600V, 60A Field Stop IGBT

#### **Features**

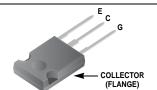
- Maximum Junction Temperature : T<sub>J</sub> = 175°C
- Positive Temperaure Co-efficient for easy parallel operating
- · High current capability
- Low saturation voltage:  $V_{CE(sat)} = 1.8V(Typ.)$  @  $I_C = 60A$
- · High input impedance
- · Tightened Parameter Distribution
- · RoHS compliant
- Qualified to Automotive Requirements of AEC-Q101



Using Novel Field Stop IGBT Technology, Fairchild's new series of Field Stop Trench IGBTs offer the optimum performance for Automotive chargers, Solar Inverter, UPS and Digital Power Generator where low conduction and switching losses are essential.

#### **Applications**

- Automotive chargers, Converters, High Voltage Auxiliaries
- Solar Inverters, UPS, SMPS, PFC





#### **Absolute Maximum Ratings**

Symbol	Description		Ratings	Units
V <sub>CES</sub>	Collector to Emitter Voltage		600	V
V <sub>GES</sub>	Gate to Emitter Voltage		± 20	V
I <sub>C</sub>	Collector Current	@ T <sub>C</sub> = 25°C	120	А
·C	Collector Current	@ T <sub>C</sub> = 100°C	60	А
I <sub>CM (1)</sub>	Pulsed Collector Current	180	А	
I <sub>F</sub>	Diode Forward Current	@ T <sub>C</sub> = 25°C	60	А
	Diode Forward Current	@ T <sub>C</sub> = 100°C	30	А
I <sub>FM(1)</sub>	Pulsed Diode Maximum Forward Current		180	А
P <sub>D</sub>	Maximum Power Dissipation	@ T <sub>C</sub> = 25°C	600	W
. n	Maximum Power Dissipation	@ T <sub>C</sub> = 100°C	300	W
TJ	Operating Junction Temperature	-55 to +175	°C	
T <sub>stg</sub>	Storage Temperature Range		-55 to +175	°C
T <sub>L</sub>	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds	300	°C	

#### **Thermal Characteristics**

Symbol	Parameter	Ratings	Units	
$R_{\theta JC}(IGBT)_{(2)}$	Thermal Resistance, Junction to Case	0.25	°C/W	
$R_{\theta JC}(Diode)$	Thermal Resistance, Junction to Case	1.1	°C/W	

Symbol	Parameter	Тур.	Units	
$R_{ heta JA}$	Thermal Resistance, Junction to Ambient (PCB Mount)(2)	45	°C/W	

## **Package Marking and Ordering Information**

<b>Device Marking</b>	Device	Package	Packing Type	Qty per Tube
FGH60N60SMD	FGH60N60SMD_F085	TO-247	Tube	30ea

For Fairchild's definition of "green" Eco Status, please visit: http://www.fairchildsemi.com/company/green/rohs\_green.html.

#### Electrical Characteristics of the IGBT T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Charac	teristics					
BV <sub>CES</sub>	Collector to Emitter Breakdown Voltage	$V_{GE} = 0V, I_{C} = 250uA$	600	-	-	V
$\frac{\Delta BV_{CES}}{\Delta T_{J}}$	Temperature Coefficient of Breakdown Voltage	V <sub>GE</sub> = 0V, I <sub>C</sub> = 250uA	-	0.22	-	V/°C
I <sub>CES</sub>	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0V$	-	-	250	
		I <sub>CES</sub> at 80%*B <sub>VCES</sub> , 175°C	-	-	1100	μΑ
I <sub>GES</sub>	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$	-	-	±400	nA
On Charac	teristics					
V <sub>GE(th)</sub>	G-E Threshold Voltage	I <sub>C</sub> = 250uA, V <sub>CE</sub> = V <sub>GE</sub>	3.5	4.7	6.0	V
		I <sub>C</sub> = 60A, V <sub>GE</sub> = 15V	-	1.8	2.5	V
V <sub>CE(sat)</sub>	Collector to Emitter Saturation Voltage	I <sub>C</sub> = 60A, V <sub>GE</sub> = 15V, T <sub>C</sub> = 175°C	-	2.14	-	V
Dynamic C	haracteristics					
C <sub>ies</sub>	Input Capacitance		-	2780	3700	pF
C <sub>oes</sub>	Output Capacitance	$V_{CE} = 30V_{,} V_{GE} = 0V_{,}$ f = 1MHz	-	260	345	pF
C <sub>res</sub>	Reverse Transfer Capacitance	1 = 11/11/12	-	80	110	pF
Switching	Characteristics					
t <sub>d(on)</sub>	Turn-On Delay Time		-	22	29	ns
t <sub>r</sub>	Rise Time		-	46	60	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{CC} = 400V, I_{C} = 60A,$	-	116	151	ns
t <sub>f</sub>	Fall Time	$R_G = 3\Omega$ , $V_{GE} = 15V$ ,	-	14	18	ns
E <sub>on</sub>	Turn-On Switching Loss	Inductive Load, T <sub>C</sub> = 25°C	-	1.59	2.23	mJ
E <sub>off</sub>	Turn-Off Switching Loss		-	0.39	0.55	mJ
E <sub>ts</sub>	Total Switching Loss		-	1.98	2.78	mJ
t <sub>d(on)</sub>	Turn-On Delay Time		-	22	28	ns
t <sub>r</sub>	Rise Time		-	44	58	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{CC} = 400V, I_{C} = 60A,$	-	124	161	ns
t <sub>f</sub>	Fall Time	$R_G = 3\Omega$ , $V_{GE} = 15V$ , Inductive Load, $T_C = 175^{\circ}C$	-	15	20	ns
E <sub>on</sub>	Turn-On Switching Loss		-	2.41	3.13	mJ
E <sub>off</sub>	Turn-Off Switching Loss		-	1.08	1.42	mJ
E <sub>ts</sub>	Total Switching Loss		-	3.49	4.55	mJ

#### Notes:

2:Rthjc for TO-247: according to Mil standard 883-1012 test method. Rthja for TO-247: according to JESD51-2, test method environmental condition and JESD51-10, test boards for through hole perimeter leaded package thermal measurements. JESD51-3: Low Effective Thermal Conductivity Test Board for Leaded Surface Mount Package.

<sup>1:</sup>Repetitive rating: Pulse width limited by max junction temperature.

## **Electrical Characteristics of the IGBT** (Continued)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max	Units
$Q_g$	Total Gate Charge		-	187	280	nC
Q <sub>ge</sub>	Gate to Emitter Charge	$V_{CE} = 400V, I_{C} = 60A,$ $V_{GE} = 15V$	-	20	29	nC
Q <sub>gc</sub>	Gate to Collector Charge	VGE - 10 V	i	92	138	nC

# Electrical Characteristics of the Diode $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions		Min.	Тур.	Max	Units
V <sub>FM</sub> Diode	Diode Forward Voltage	I <sub>E</sub> = 30A	$T_C = 25^{\circ}C$	-	2.1	2.7	V
	2.000 r ormana romage		$T_{\rm C} = 175^{\rm o}{\rm C}$	-	1.48	-	] '
t <sub>rr</sub>	Diode Reverse Recovery Time  Diode Reverse Recovery Charge	- I <sub>F</sub> =30A, dI <sub>F</sub> /dt = 200A/μs	$T_C = 25^{\circ}C$	-	33	42	ns
11			$T_{\rm C} = 175^{\rm o}{\rm C}$	-	115	-	
Q.,			$T_C = 25^{\circ}C$	-	53	69	nC
311			$T_{\rm C} = 175^{\rm o}{\rm C}$	-	606	-	

**Figure 1. Typical Output Characteristics** 

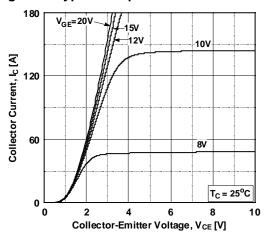


Figure 3. Typical Saturation Voltage Characteristics

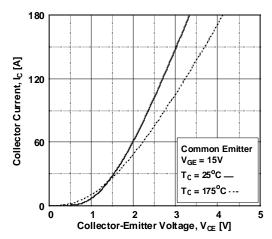


Figure 5. Saturation Voltage vs. Case
Temperature at Variant Current Level

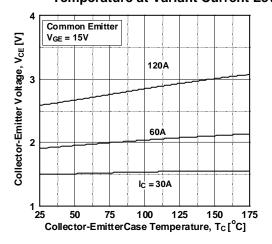


Figure 2. Typical Output Characteristics

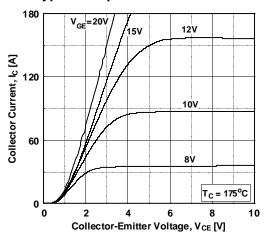


Figure 4. Transfer Characteristics

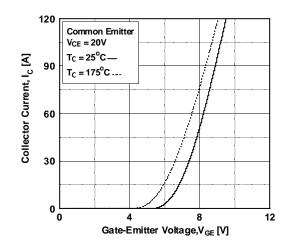


Figure 6. Saturation Voltage vs.  $V_{\text{GE}}$ 

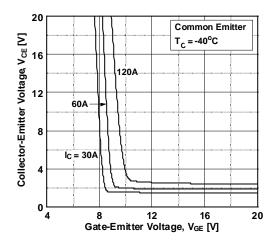


Figure 7. Saturation Voltage vs. V<sub>GE</sub>

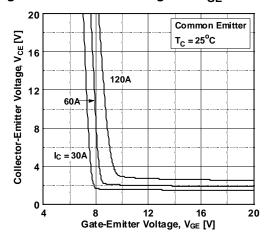


Figure 9. Capacitance Characteristics

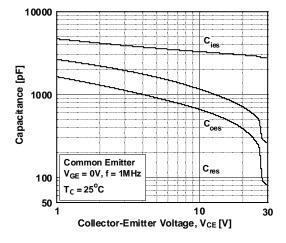


Figure 11. SOA Characteristics

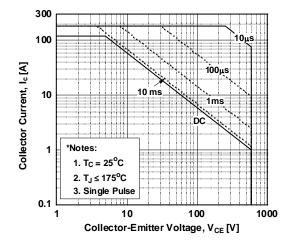


Figure 8. Saturation Voltage vs. V<sub>GE</sub>

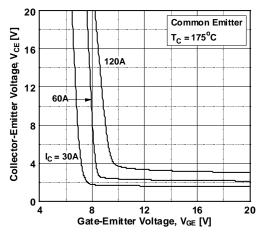


Figure 10. Gate charge Characteristics

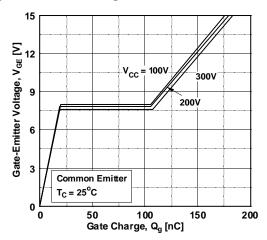


Figure 12. Turn-on Characteristics vs.
Gate Resistance

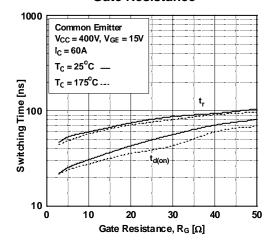


Figure 13. Turn-off Characteristics vs.
Gate Resistance

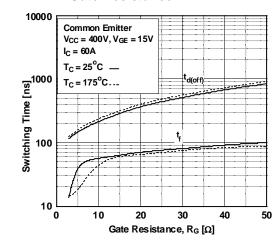


Figure 15. Turn-off Characteristics vs. Collector Current

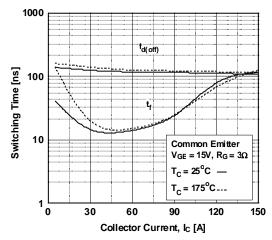


Figure 17. Switching Loss vs. Collector Current

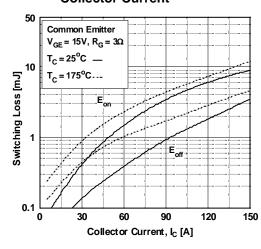


Figure 14. Turn-on Characteristics vs. Collector Current

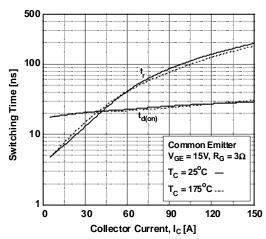


Figure 16. Switching Loss vs.
Gate Resistance

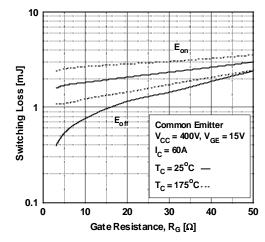


Figure 18. Turn off Switching SOA Characteristics

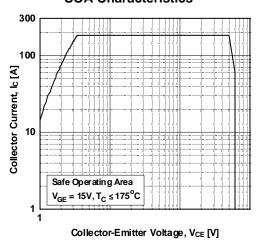


Figure 19. Forward Characteristics

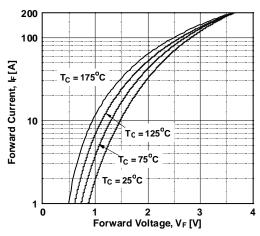


Figure 20. Reverse Recovery Current

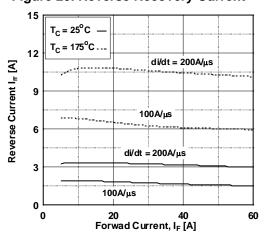


Figure 21. Stored Charge

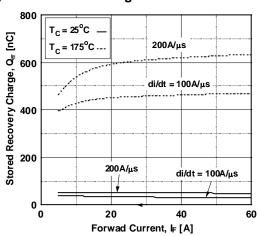


Figure 22. Reverse Recovery Time

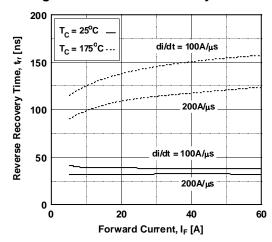
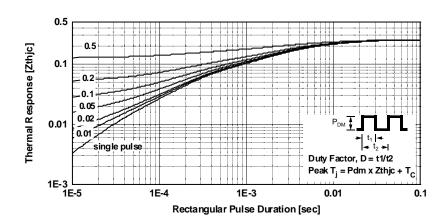
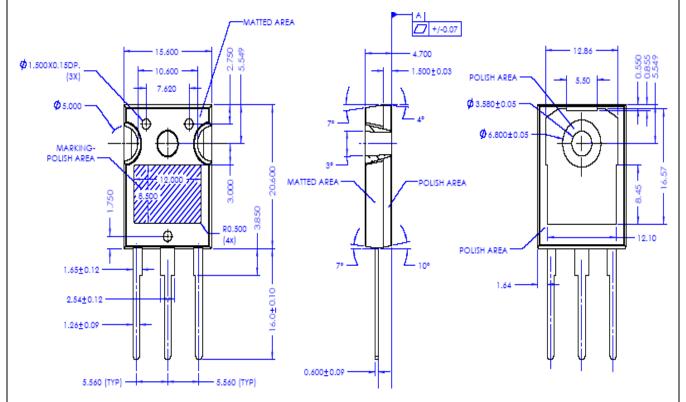


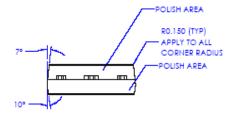
Figure 23. Transient Thermal Impedance of IGBT





# TO - 247AB (FKS PKG CODE 001)









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